molex



Part Number : 754515002
Product Description : Small Form-factor Pluggable (SFP) Stacked 2-by-6 Multi-Port Connector with 2 Inner Lightpipes, with Press-fit PC Tails, 240 Circuits, Lead-Free
Series Number : 75451
Status : Active
Product Category : High-Speed I/O Connectors

Documents & Resources

Drawings

754515002_sd.pdf

3D Models and Design Files

STEP AP242

SOLIDWORKS

Creo

Specifications

AS-75310-001-001.pdf

AS-76090-001-001.pdf

PK-75451-001-001.pdf

PS-75310-001-001.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	per SJ/T 11365-2006
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2025)4165-DC (25 June 2025)
EU RoHS	Compliant per EU 2015/863

Compliance Statements

- EU RoHS
- REACH SVHC
- Low-Halogen

Industry Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

Substances of Interest

- PFAS

EU RoHS Certificate of Compliance

Additional Product Compliance Information

Part Details

General

Status	Active
Category	High-Speed I/O Connectors
Series	75451
Description	Small Form-factor Pluggable (SFP) Stacked 2-by-6 Multi-Port Connector with 2 Inner Lightpipes, with Press-fit PC Tails, 240 Circuits, Lead-Free
Application	Module-to-Board
Comments	With 2 Inner Lightpipes
Component Type	Receptacle
Product Name	SFP
Type	Pluggable
UPC	822350126007

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	0.5A

Data Rate	10.0 Gbps
Shielded	Yes
Shield Type	EMI Fingers
Voltage - Maximum	30V

Physical

Circuits (Loaded)	240
Circuits (maximum)	240
Color - Resin	Black, Clear (Blue Tint)
Durability (mating cycles max)	200
Flammability	94V-0
Lock to Mating Part	Yes
Material - Metal	High Performance Alloy (HPA)
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic, Polycarbonate
Net Weight	146.342/g
Orientation	Right Angle
Packaging Type	Tray
Panel Mount	No
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	2.40mm
PC Tail Length	3.05mm
Pitch - Mating Interface	0.80mm
Plating min - Mating	0.762µm
Plating min - Termination	0.762µm
Polarized to Mating Part	Yes
Polarized to PCB	Yes
Temperature Range - Operating	-40° to +85°C
Termination Interface Style	Through Hole - Compliant Pin
Waterproof / Dustproof	No

Solder Process Data

Lead-Free Process Capability	N/A

Application Tooling